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L8 and cmp	6

Database:	US Pre-Grant Publication Full-Text Database US Patents Full-Text Database US OCR Full-Text Database EPO Abstracts Database JPO Abstracts Database Derwent World Patents Index IBM Technical Disclosure Bulletins
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Search:	L9	Refine Search
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		Interrupt

Search HistoryDATE: Tuesday, September 21, 2004 [Printable Copy](#) [Create Case](#)**Set Name Query**
side by side

DB=USPT; PLUR=YES; OP=ADJ

Set Name	Query	Hit Count	Set Name
			result set
<u>L9</u>	L8 and cmp	6	<u>L9</u>
<u>L8</u>	L5 and (flow adj rate) and sccm and watts and nitride	8	<u>L8</u>
<u>L7</u>	L4 and copper	5	<u>L7</u>
<u>L6</u>	L3 and copper	8	<u>L6</u>
<u>L5</u>	L2 and copper	120	<u>L5</u>
<u>L4</u>	L3 and ammonia	5	<u>L4</u>
<u>L3</u>	L2 and (hydrogen adj plasma)	8	<u>L3</u>
<u>L2</u>	porous near (low adj K)	130	<u>L2</u>
<u>L1</u>	porous near (low adj K)	130	<u>L1</u>

END OF SEARCH HISTORY

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Search Results - Record(s) 1 through 6 of 6 returned.

1. Document ID: US 6790770 B2

L9: Entry 1 of 6

File: USPT

Sep 14, 2004

US-PAT-NO: 6790770

DOCUMENT-IDENTIFIER: US 6790770 B2

TITLE: Method for preventing photoresist poisoning

2. Document ID: US 6737747 B2

L9: Entry 2 of 6

File: USPT

May 18, 2004

US-PAT-NO: 6737747

DOCUMENT-IDENTIFIER: US 6737747 B2

TITLE: Advanced BEOL interconnect structures with low-k PE CVD cap layer and method thereof

3. Document ID: US 6723635 B1

L9: Entry 3 of 6

File: USPT

Apr 20, 2004

US-PAT-NO: 6723635

DOCUMENT-IDENTIFIER: US 6723635 B1

TITLE: Protection low-k ILD during damascene processing with thin liner

4. Document ID: US 6576545 B1

L9: Entry 4 of 6

File: USPT

Jun 10, 2003

US-PAT-NO: 6576545

DOCUMENT-IDENTIFIER: US 6576545 B1

TITLE: Semiconductor devices with dual nature capping/ARC layers on fluorine doped silica glass inter-layer dielectrics and method of forming capping/ARC layers

[Full](#) | [Title](#) | [Citation](#) | [Front](#) | [Review](#) | [Classification](#) | [Date](#) | [Reference](#) | [Claims](#) | [KUIC](#) | [Drawn Ds](#)

5. Document ID: US 6525428 B1

L9: Entry 5 of 6

File: USPT

Feb 25, 2003

US-PAT-NO: 6525428

DOCUMENT-IDENTIFIER: US 6525428 B1

TITLE: Graded low-k middle-etch stop layer for dual-inlaid patterning

[Full](#) | [Title](#) | [Citation](#) | [Front](#) | [Review](#) | [Classification](#) | [Date](#) | [Reference](#) | [Claims](#) | [KUIC](#) | [Drawn Ds](#)

6. Document ID: US 6323121 B1

L9: Entry 6 of 6

File: USPT

Nov 27, 2001

US-PAT-NO: 6323121

DOCUMENT-IDENTIFIER: US 6323121 B1

TITLE: Fully dry post-via-etch cleaning method for a damascene process

[Full](#) | [Title](#) | [Citation](#) | [Front](#) | [Review](#) | [Classification](#) | [Date](#) | [Reference](#) | [Claims](#) | [KUIC](#) | [Drawn Ds](#)

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1. Document ID: US 6693043 B1

L7: Entry 1 of 5

File: USPT

Feb 17, 2004

US-PAT-NO: 6693043

DOCUMENT-IDENTIFIER: US 6693043 B1

TITLE: Method for removing photoresist from low-k films in a downstream plasma system

Full	Title	Citation	Front	Review	Classification	Date	Reference	Claims	KUMC	Drawn D
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2. Document ID: US 6673725 B2

L7: Entry 2 of 5

File: USPT

Jan 6, 2004

US-PAT-NO: 6673725

DOCUMENT-IDENTIFIER: US 6673725 B2

TITLE: Semiconductor device and method of manufacturing the same

Full	Title	Citation	Front	Review	Classification	Date	Reference	Claims	KUMC	Drawn D
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3. Document ID: US 6638875 B2

L7: Entry 3 of 5

File: USPT

Oct 28, 2003

US-PAT-NO: 6638875

DOCUMENT-IDENTIFIER: US 6638875 B2

TITLE: Oxygen free plasma stripping process

Full	Title	Citation	Front	Review	Classification	Date	Reference	Claims	KUMC	Drawn D
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4. Document ID: US 6630406 B2

L7: Entry 4 of 5

File: USPT

Oct 7, 2003

US-PAT-NO: 6630406

DOCUMENT-IDENTIFIER: US 6630406 B2

TITLE: Plasma ashing process

[Full](#) | [Title](#) | [Citation](#) | [Front](#) | [Review](#) | [Classification](#) | [Date](#) | [Reference](#) | [Claims](#) | [KOMC](#) | [Drawn Ds](#)

5. Document ID: US 6281135 B1

L7: Entry 5 of 5

File: USPT

Aug 28, 2001

US-PAT-NO: 6281135

DOCUMENT-IDENTIFIER: US 6281135 B1

TITLE: Oxygen free plasma stripping process

[Full](#) | [Title](#) | [Citation](#) | [Front](#) | [Review](#) | [Classification](#) | [Date](#) | [Reference](#) | [Claims](#) | [KOMC](#) | [Drawn Ds](#)

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Search Results - Record(s) 1 through 5 of 5 returned.

1. Document ID: US 6693043 B1

L4: Entry 1 of 5

File: USPT

Feb 17, 2004

US-PAT-NO: 6693043

DOCUMENT-IDENTIFIER: US 6693043 B1

TITLE: Method for removing photoresist from low-k films in a downstream plasma system

Full	Title	Citation	Front	Review	Classification	Date	Reference	Claims	KMPC	Drawn D
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2. Document ID: US 6673725 B2

L4: Entry 2 of 5

File: USPT

Jan 6, 2004

US-PAT-NO: 6673725

DOCUMENT-IDENTIFIER: US 6673725 B2

TITLE: Semiconductor device and method of manufacturing the same

Full	Title	Citation	Front	Review	Classification	Date	Reference	Claims	KMPC	Drawn D
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3. Document ID: US 6638875 B2

L4: Entry 3 of 5

File: USPT

Oct 28, 2003

US-PAT-NO: 6638875

DOCUMENT-IDENTIFIER: US 6638875 B2

TITLE: Oxygen free plasma stripping process

Full	Title	Citation	Front	Review	Classification	Date	Reference	Claims	KMPC	Drawn D
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4. Document ID: US 6630406 B2

L4: Entry 4 of 5

File: USPT

Oct 7, 2003

US-PAT-NO: 6630406

DOCUMENT-IDENTIFIER: US 6630406 B2

TITLE: Plasma ashing process

Full	Title	Citation	Front	Review	Classification	Date	Reference				Claims	KWIC	Drawn Ds
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5. Document ID: US 6281135 B1

L4: Entry 5 of 5

File: USPT

Aug 28, 2001

US-PAT-NO: 6281135

DOCUMENT-IDENTIFIER: US 6281135 B1

TITLE: Oxygen free plasma stripping process

Full	Title	Citation	Front	Review	Classification	Date	Reference				Claims	KWIC	Drawn Ds
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